





# Low Common-Mode Noise Full-Bridge *LLC* Resonant Converter With Balanced Resonant Tank

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**Abstract**—This article proposes a low common-mode (CM) noise full-bridge *LLC* resonant converter with two balanced resonant tanks. In the proposed converter, each resonant inductor and capacitor is divided into two components with the same value. The CM current flowing through parasitic capacitors of the transformer is reduced due to the balanced resonant tank. Moreover, the CM noise can be significantly reduced by adjacently locating the primary and secondary layers with the same  $dv/dt$  characteristic. Therefore, the proposed converter decreases the CM noise generated from the planar transformer (PT) by the balanced resonant tank and proposed layer arrangement of PT and achieves a high power density with a decreased size of the electromagnetic interference filter. The validity of the proposed converter is verified by a 1.5-kW prototype with 400-V input and 270–420-V output.

**Index Terms**—Common mode (CM) noise, planar transformer (PT), *LLC* resonant converter.

## I. INTRODUCTION

COMMON-MODE (CM) noise in power converters generates an electromagnetic interference (EMI), which can disrupt electronic devices, equipment, and systems [1]. In order to mitigate the EMI issue, the EMI filter, including the CM choke and *Y*-capacitor, is required. Despite the necessity of the EMI filter, it can be a burden of power density because the size of the EMI filter becomes larger as the level of CM noise becomes higher [2]. Therefore, a low CM noise is necessary for a high-power-density converter.

The CM noise is mostly caused by the CM current flowing through parasitic capacitors with high  $dv/dt$  nodes, such as the parasitic capacitors of MOSFETs and transformer [3]–[6]. Among them, the parasitic capacitors of the transformer present a high level of CM current. Especially, the planar transformer (PT) has a much larger parasitic capacitance comparing with the wire-wound transformer because the overlapped area of the layer

in the PT is much wider. A large capacitance with large  $dv/dt$  difference between parasitic capacitors results in severe CM noise. Although the PT is an attractive solution for designing a small volume of magnetics, it leads to a large volume of the EMI filter. Thus, it is necessary to reduce the CM noise generated from the PT.

Various works for reducing the CM noise generated from the PT have been studied [7]–[24]. The first category is reducing the CM noise based on the circuit variation, such as winding cancellation, passive component cancellation, symmetrical circuit configuration, and so on [7]–[14]. The works in [7] and [8] utilize an additional transformer winding named antiphase winding for good CM noise attenuation, and previous research works in [9] and [10] achieve a low CM noise by adding passive components, such as the capacitor and inductor. Other approaches in [11]–[13] suggest the symmetrical circuit configuration, which can eliminate the CM noise current flowing through the parasitic capacitor of the transformer. Although they improve the EMI performance by canceling the CM current flowing through the parasitic capacitors of the transformer, additional components or windings degrade the power density of the converter. In [14], it gets a better CM noise attenuation by changing the location of the transformer and rectifier diodes. This scheme is simple because the additional components or windings are not required. However, methods [7]–[14] have limited improvement of CM noise reduction because they do not consider the CM noise generated from parasitic capacitors between each layer of the transformer. That CM noise is especially a critical factor of the PT compared with the wire-wound transformer because there are large parasitic capacitances between adjacent layers in the PT by the large overlapped area of layers.

The secondary category was focused on reducing the CM noise generated from the parasitic capacitor between the adjacent layers of the PT, and many works have been studied [15]–[24]. Previous works in [15]–[19] use the shielding layer between the primary and secondary layers to suppress the CM noise. However, extra windings for shielding should be added and they increase the winding area of the transformer. There is a large conduction loss in shielding layers due to the eddy current. Although Fei *et al.* [20] can relieve the conduction loss of the primary circuit by utilizing half of the shielding layer as the primary turn, it still requires the shielding layer for every space between primary and secondary windings. In [21]–[24], adjacent primary and secondary layers have the same  $dv/dt$  characteristic, and there is no CM current flowing through

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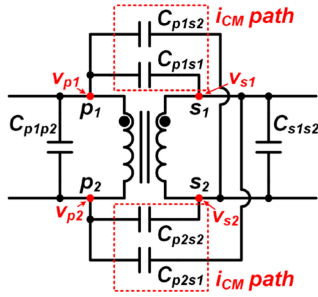


Fig. 1. Parasitic capacitor model of the transformer.

parasitic capacitors between layers. However, those schemes are adopted to the half-bridge *LLC* resonant converter, flyback converter, and forward converter. Thus, it is difficult to utilize them for medium-to-high power applications due to the large conduction loss in the primary-side circuit.

This article proposes a CM noise reduction method for the full-bridge (FB) *LLC* resonant converter, and it can be adopted for medium-to-high power applications, such as the electric vehicle system, due to a high voltage gain and small primary current [25], [26]. The proposed converter has a new circuit configuration and layer arrangement of the PT, and they can significantly reduce the CM noise. The resonant inductor and capacitor are equally divided into two components to make the symmetric circuit structure and have the equivalently same values with the conventional converter. So that, static points, which have zero  $dv/dt$  characteristic, on the primary and secondary side of the transformer can be generated. The primary and secondary layer can have the same  $dv/dt$  by proposing a layer arrangement for PT based on the proposed converter. As a result, the proposed two major key ideas, the balanced resonant tank and layer arrangement of the PT, can decrease the CM noise generated from the CM current flowing through parasitic capacitors in the PT and achieve high power density by reducing the size of the EMI filter.

The rest of this article is organized as follows. In Section II, the CM noise of the conventional and proposed FB *LLC* resonant converters according to each operational mode is explained. Section III suggests a layer arrangement of the transformer in the proposed converter. In Section IV, the proposed converter is verified by the experimental results of the prototype with 400-V input and 1.5-kW (270–420 V/3.57 A) output. Finally, Section V summarizes the effectiveness of the proposed converter with the conclusion.

## II. CM NOISE OF FB *LLC* RESONANT CONVERTER ACCORDING TO THE OPERATIONAL PRINCIPLE

### A. CM Noise Characteristic in the Conventional Converter

The CM noise generated from the PT is caused by the CM current  $i_{CM}$ , which is flowing through parasitic capacitors between primary and secondary layers. Fig. 1 shows a parasitic capacitor model of the transformer. If the transformer is constructed symmetrically, it can be assumed that  $C_{p1s1} = C_{p2s2}$

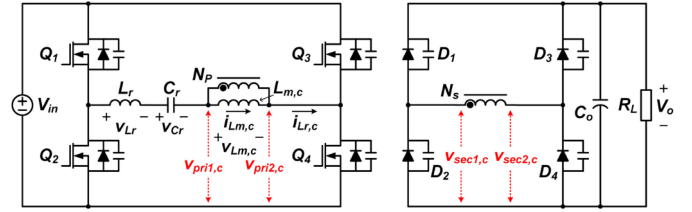


Fig. 2. Circuit diagram of the conventional converter.

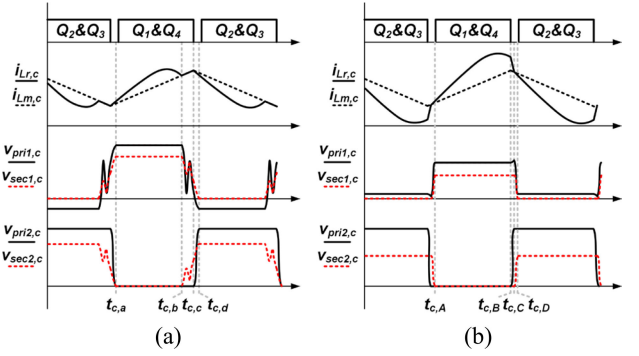


Fig. 3. Operational waveform of the conventional converter. (a) Under the below region. (b) Under the above region.

$C_{p1s2} = C_{p2s1}$ , and  $i_{CM}$  can be expressed as follows [23]:

$$i_{CM} = C_{p1s1} \left\{ \left( \frac{dv_{p1}}{dt} - \frac{dv_{s1}}{dt} \right) + \left( \frac{dv_{p2}}{dt} - \frac{dv_{s2}}{dt} \right) \right\} + C_{p1s2} \left\{ \left( \frac{dv_{p1}}{dt} - \frac{dv_{s2}}{dt} \right) + \left( \frac{dv_{p2}}{dt} - \frac{dv_{s1}}{dt} \right) \right\} \quad (1)$$

where  $C_{p1s1}$ ,  $C_{p1s2}$ ,  $C_{p2s1}$ , and  $C_{p2s2}$  are the parasitic capacitors between the primary and secondary side of the transformer, and  $v_{p1}$ ,  $v_{p2}$ ,  $v_{s1}$ , and  $v_{s2}$  are the voltage versus ground at the point  $p_1$ ,  $p_2$ ,  $s_1$ , and  $s_2$ , respectively, as shown in Fig. 1.

According to (1),  $i_{CM}$  is proportional to the  $dv/dt$  difference between the primary and secondary side terminals of the transformer. Thus, a small  $dv/dt$  difference is necessary for small  $i_{CM}$ . In the case of parasitic capacitors between two different primary or secondary layers, there is no CM current between layers.

Fig. 2 shows a circuit diagram of the conventional FB *LLC* resonant converter. The turn-ON time of  $Q_1$  is complementary to that of  $Q_2$  with a dead time, and the same gate signals are applied to  $Q_3$  and  $Q_4$ . The operating region in the *LLC* resonant converter can be divided into two regions, the below and above regions, depending on the operating switching frequency [28]. The below region means that the operating switching frequency is lower than the resonant frequency, and the above region is the opposite operation region, i.e., the operating switching frequency is higher than the resonant frequency. Fig. 3 shows the key operating waveforms of the conventional converter under below and above regions. The operation of the *LLC* resonant converter is divided based on [27] and the CM current of each mode will be discussed.

Fig. 4 shows an equivalent circuit at the primary and secondary-side circuit during both operations from  $t_{c,a}$  to  $t_{c,b}$

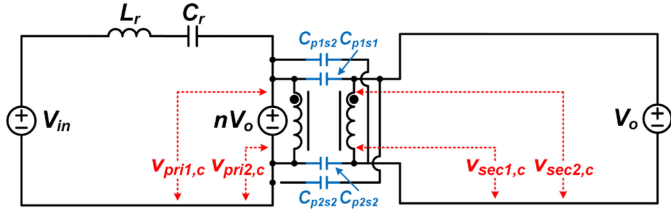


Fig. 4. Equivalent circuit of the conventional converter during the operation from  $t_{c,a}$  to  $t_{c,b}$  and from  $t_{c,A}$  to  $t_{c,B}$ .

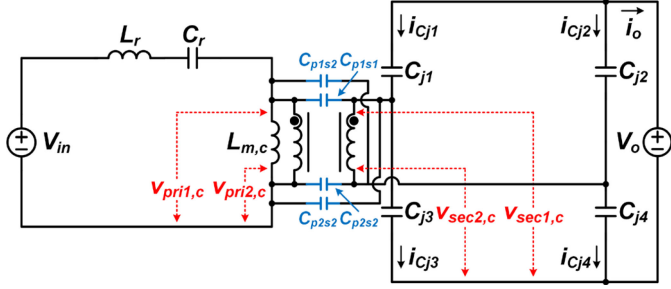


Fig. 5. Equivalent circuit of the conventional converter during the operation from  $t_{c,b}$  to  $t_{c,c}$ .

and from  $t_{c,A}$  to  $t_{c,B}$ . During these operations, the voltage across the magnetizing inductor  $v_{Lm,c}$  is the turns-ratio of the transformer  $n$  times the output voltage  $V_o$ . Also, secondary diodes  $D_1$  and  $D_4$  are conducted. Therefore, the voltage potential versus ground at the terminals of the transformer in the conventional converter and their  $dv/dt$  characteristics can be calculated as follows:

$$v_{pri1,c} = nV_o \quad (2)$$

$$v_{pri2,c} = 0 \quad (3)$$

$$v_{sec1,c} = V_o \quad (4)$$

$$v_{sec2,c} = 0 \quad (5)$$

$$\frac{dv_{pri1,c}}{dt} = \frac{dv_{pri2,c}}{dt} = \frac{dv_{sec1,c}}{dt} = \frac{dv_{sec2,c}}{dt} = 0 \quad (6)$$

where  $v_{pri1,c}$  and  $v_{pri2,c}$  are, respectively, the voltage potentials versus ground at the primary-side terminals of the transformer in the conventional converter, and  $v_{sec1,c}$  and  $v_{sec2,c}$  are, respectively, the voltage potentials versus ground at the secondary-side terminals of the transformer in the conventional converter.

From (1) and (6), the CM current of the conventional converter in Fig. 4  $i_{CM,c1}$  is zero.

Fig. 5 shows an equivalent circuit at the primary and secondary sides from  $t_{c,b}$  to  $t_{c,c}$ .  $V_o$  is not reflected on the primary side because there is no current flowing through the secondary diode. Thus, the equivalent circuit at the primary side is composed of the resonant inductor  $L_r$ , resonant capacitor  $C_r$ , and magnetizing inductor  $L_{m,c}$ , and  $v_{pri1,c}$ ,  $v_{pri2,c}$  and  $dv/dt$  characteristics of the primary-side terminals can be expressed as follows:

$$v_{pri1,c} = v_{Lm,c} \quad (7)$$

$$\frac{dv_{pri1,c}}{dt} = \frac{dv_{Lm,c}}{dt} \quad (8)$$

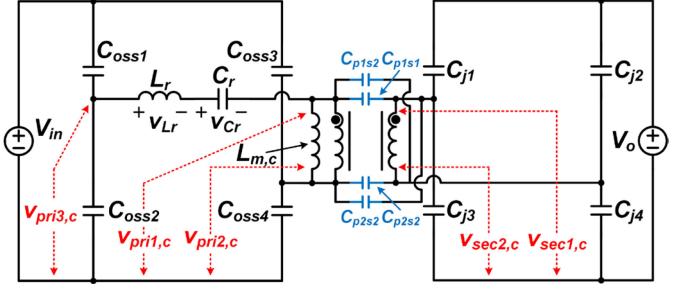


Fig. 6. Equivalent circuit of the conventional converter during the operation from  $t_{c,B}$  to  $t_{c,C}$ .

$$v_{pri2,c} = \frac{dv_{pri2,c}}{dt} = 0. \quad (9)$$

Assuming the parasitic capacitors of secondary diodes  $C_{j1}$ ,  $C_{j2}$ ,  $C_{j3}$ , and  $C_{j4}$  are the same, the magnitude of the current flowing through the junction capacitor of rectifier diodes is the same, i.e.,  $i_{Cj1} = -i_{Cj2} = -i_{Cj3} = i_{Cj4}$  because the output current  $i_o$  is zero. Also, voltages across  $C_{j1}$  and  $C_{j4}$  are the same, and the voltage across  $C_{j2}$  and  $C_{j3}$  are the same. Thus, the relationship between  $v_{sec1,c}$  and  $v_{sec2,c}$  can be obtained as follows:

$$v_{sec1,c} + v_{sec2,c} = V_o \quad (10)$$

$$v_{sec1,c} - v_{sec2,c} = \frac{v_{Lm,c}}{n}. \quad (11)$$

From (10) and (11),  $v_{sec1,c}$ ,  $v_{sec2,c}$ , and  $dv/dt$  characteristic of the secondary-side terminals can be calculated as follows:

$$v_{sec1,c} = \frac{1}{2} \left( V_o + \frac{v_{Lm,c}}{n} \right) \quad (12)$$

$$v_{sec2,c} = \frac{1}{2} \left( V_o - \frac{v_{Lm,c}}{n} \right) \quad (13)$$

$$\frac{dv_{sec1,c}}{dt} = -\frac{dv_{sec2,c}}{dt} = \frac{1}{2n} \frac{dv_{Lm,c}}{dt}. \quad (14)$$

Using (1), (6), and (14), the CM current during the operation in Fig. 5  $i_{CM,c2}$  can be calculated as follows:

$$i_{CM,c2} = \frac{dv_{Lm,c}}{dt} \left\{ C_{p1s1} \left( 1 - \frac{1}{2n} \right) + C_{p1s2} \left( 1 + \frac{1}{2n} \right) \right\}. \quad (15)$$

Fig. 6 shows an equivalent circuit at the primary and secondary side from  $t_{c,B}$  to  $t_{c,C}$ . During this operation, the primary switches are turned OFF, and the current flows through secondary diodes. The relationship between  $v_{pri1,c}$ ,  $v_{pri2,c}$ , and  $v_{pri3,c}$  can be obtained as follows:

$$v_{pri2,c} + v_{pri3,c} = V_{in} \quad (16)$$

$$v_{pri1,c} - v_{pri2,c} = nV_o \quad (17)$$

$$v_{pri3,c} - v_{pri1,c} = v_{Lr} + v_{Cr} \quad (18)$$

where  $v_{Lr}$  is the voltage across the  $L_r$  and  $v_{Cr}$  is the voltage across the  $C_r$ .

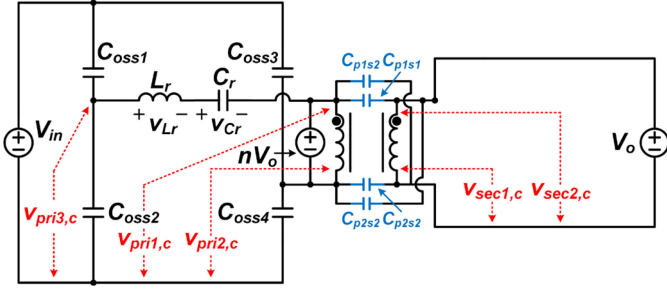


Fig. 7. Equivalent circuit of the conventional converter during both operations from  $t_{c,c}$  to  $t_{c,d}$  and from  $t_{c,C}$  to  $t_{c,D}$ .

Using (16)–(18),  $v_{pri1,c}$ ,  $v_{pri2,c}$  and the  $dv/dt$  characteristic of primary-side terminals can be expressed as follows:

$$v_{pri1,c} = \frac{1}{2} (V_{in} + nV_o - v_{Lr} - v_{Cr}) \quad (19)$$

$$v_{pri2,c} = \frac{1}{2} (V_{in} - nV_o - v_{Lr} - v_{Cr}) \quad (20)$$

$$\frac{dv_{pri1,c}}{dt} = \frac{dv_{pri2,c}}{dt} = -\frac{1}{2} \left( \frac{dv_{Lr}}{dt} + \frac{dv_{Cr}}{dt} \right). \quad (21)$$

The equivalent circuit on the secondary side is the same as the secondary circuit in Fig. 5. Thus,  $dv/dt$  of  $v_{sec1,c}$  and  $v_{sec2,c}$  can be calculated from (14). Using (1), (14), and (21), the CM current during the operation in Fig. 6  $i_{CM,c3}$  can be calculated as follows:

$$i_{CM,c3} = -C_{p1s1} \left( \frac{dv_{Lr}}{dt} + \frac{dv_{Cr}}{dt} + \frac{1}{n} \frac{dv_{Lm,c}}{dt} \right) - C_{p1s2} \left( \frac{dv_{Lr}}{dt} + \frac{dv_{Cr}}{dt} - \frac{1}{n} \frac{dv_{Lm,c}}{dt} \right). \quad (22)$$

Fig. 7 shows an equivalent circuit at the primary and secondary sides from  $t_{c,c}$  to  $t_{c,d}$  and from  $t_{c,C}$  to  $t_{c,D}$ . During these operations, primary switches are turned OFF, and the current does not flow through secondary diodes. The equivalent circuit at the primary side is similar to the primary circuit in Fig. 6, and  $v_{pri1,c}$ ,  $v_{pri2,c}$ , and the  $dv/dt$  characteristic of primary-side terminals can be calculated as follows:

$$v_{pri1,c} = \frac{1}{2} \left\{ V_{in} - v_{Cr} + v_{Lm,c} \left( 1 - \frac{L_r}{L_{m,c}} \right) \right\} \quad (23)$$

$$v_{pri2,c} = \frac{1}{2} \left\{ V_{in} - v_{Cr} - v_{Lm,c} \left( 1 + \frac{L_r}{L_{m,c}} \right) \right\} \quad (24)$$

$$\frac{dv_{pri1,c}}{dt} = -\frac{1}{2} \left\{ \frac{dv_{Cr}}{dt} - \frac{dv_{Lm,c}}{dt} \left( 1 - \frac{L_r}{L_{m,c}} \right) \right\} \quad (25)$$

$$\frac{dv_{pri2,c}}{dt} = -\frac{1}{2} \left\{ \frac{dv_{Cr}}{dt} + \frac{dv_{Lm,c}}{dt} \left( 1 + \frac{L_r}{L_{m,c}} \right) \right\}. \quad (26)$$

The equivalent circuit of the secondary side is the same as the secondary circuit in Fig. 4. Therefore,  $dv/dt$  of  $v_{sec1,c}$  and  $v_{sec2,c}$  is zero according to (6). From (1), (6), (25), and (26), a CM current during the operation in Fig. 7,  $i_{CM,c4}$ , can be

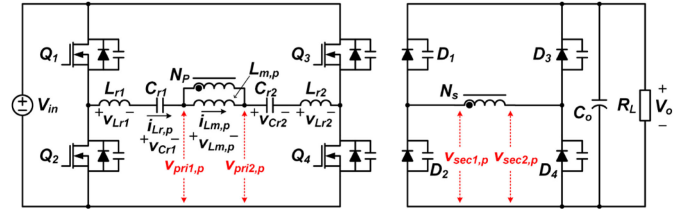


Fig. 8. Circuit diagram of the proposed converter.

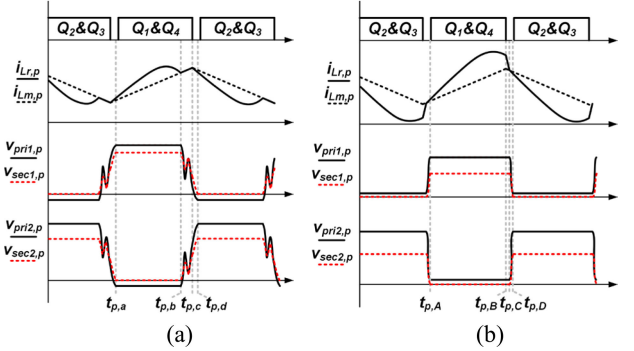


Fig. 9. Operational waveform of the proposed converter. (a) Under the below region. (b) Under the above region.

calculated as follows:

$$i_{CM,c4} = -C_{p1s1} \left\{ \frac{dv_{Cr}}{dt} + \frac{dv_{Lm,c}}{dt} \left( 1 - \frac{L_r}{L_{m,c}} \right) \right\} - C_{p1s2} \left\{ \frac{dv_{Cr}}{dt} + \frac{dv_{Lm,c}}{dt} \left( 1 + \frac{L_r}{L_{m,c}} \right) \right\}. \quad (27)$$

The secondary-side circuit of the conventional converter is symmetric based on the transformer. However, the primary-side circuit of the conventional converter is asymmetric. Thus, the  $dv/dt$  characteristics of primary and secondary-side terminals in the transformer are different, and it results in a large CM noise from the transformer.

### B. CM Noise Characteristic in the Proposed Converter

Fig. 8 shows a circuit diagram of the proposed converter. The gate signals of the proposed converter are the same as those of the conventional converter. The turns-ratio of the transformer is the same as that of the conventional converter. In the proposed converter, both resonant inductor and resonant capacitor are equally divided into two components to make a balanced resonant tank. In the real case, it is difficult to make exactly balanced resonant tanks due to the tolerance of components. In our prototype,  $L_{r1}$  and  $L_{r2}$  are integrated into the one core, and each resonant inductor is made up of windings on the side legs of the EE-shaped core.  $L_{r1}$  and  $L_{r2}$  are almost the same because half of the symmetrical EE-shaped core is applied as  $L_{r1}$  and  $L_{r2}$ , and windings made by printed circuit board (PCB) manufacture are identical.  $C_{r1}$  and  $C_{r2}$  can have the tolerance, which is commonly maximum 5%. Therefore, the CM noise of the proposed converter is mainly affected by the tolerance of the resonant capacitor. Since there are less tolerance components, such as 2%, 1%, and 0.5%, the voltage unbalance problem of



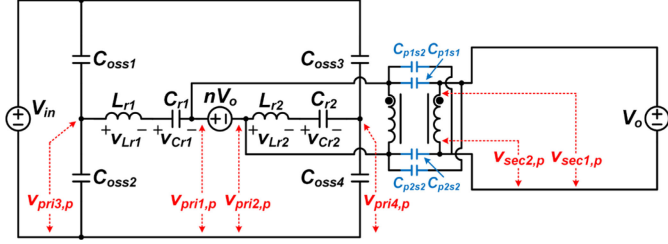


Fig. 13. Equivalent circuit of the proposed converter during the operation from  $t_{p,c}$  to  $t_{p,d}$  and from  $t_{p,c}$  to  $t_{p,D}$ .

TABLE I  
CM CURRENT COMPARISON UNDER BELOW REGION

time	$i_{CM}$ under below region	
	prop.	conv.
$t_a \sim t_b$	0	0
$t_b \sim t_c$	0	$\frac{dv_{lm}}{dt} \left\{ c_{p1s1} \left( 1 - \frac{1}{2n} \right) + c_{p1s2} \left( 1 + \frac{1}{2n} \right) \right\}$
$t_c \sim t_d$	0	$-c_{p1s1} \left\{ \frac{dv_{lr}}{dt} + \frac{dv_{lm}}{dt} \left( 1 - \frac{L_r}{L_m} \right) \right\} - c_{p1s2} \left\{ \frac{dv_{lr}}{dt} + \frac{dv_{lm}}{dt} \left( 1 + \frac{L_r}{L_m} \right) \right\}$

TABLE II  
CM CURRENT COMPARISON UNDER ABOVE REGION

time	$i_{CM}$ under above region	
	prop.	conv.
$t_A \sim t_B$	0	0
$t_B \sim t_C$	0	$-c_{p1s1} \left( \frac{dv_{lr}}{dt} + \frac{dv_{cr}}{dt} + \frac{1}{n} \frac{dv_{lm}}{dt} \right) - c_{p1s2} \left( \frac{dv_{lr}}{dt} + \frac{dv_{cr}}{dt} - \frac{1}{n} \frac{dv_{lm}}{dt} \right)$
$t_C \sim t_D$	0	$-c_{p1s1} \left\{ \frac{dv_{lr}}{dt} + \frac{dv_{lm}}{dt} \left( 1 - \frac{L_r}{L_m} \right) \right\} - c_{p1s2} \left\{ \frac{dv_{lr}}{dt} + \frac{dv_{lm}}{dt} \left( 1 + \frac{L_r}{L_m} \right) \right\}$

and  $dv/dt$  characteristics of  $v_{pri1,p}$  and  $v_{pri2,p}$  can be obtained as follows:

$$v_{pri1,p} = \frac{1}{2} (V_{in} + v_{Lm,p}) \quad (40)$$

$$v_{pri2,p} = \frac{1}{2} (V_{in} - v_{Lm,p}) \quad (41)$$

$$\frac{dv_{pri1,p}}{dt} = -\frac{dv_{pri2,p}}{dt} = \frac{1}{2} v_{Lm,p} \quad (42)$$

The equivalent circuit on the secondary side is the same as the secondary circuit in Fig. 5. Thus,  $dv/dt$  of  $v_{sec1,p}$  and  $v_{sec2,p}$  is zero according to (14). Using (1), (14), and (42), the CM current during the operation in Fig. 13  $i_{CM,p4}$  is zero.

The CM currents of the proposed converter are equal or smaller than those of the conventional converter in Section II-A under every operating condition, as listed in Tables I and II. Therefore, the CM noise in the proposed converter can be smaller than that in the conventional converter.

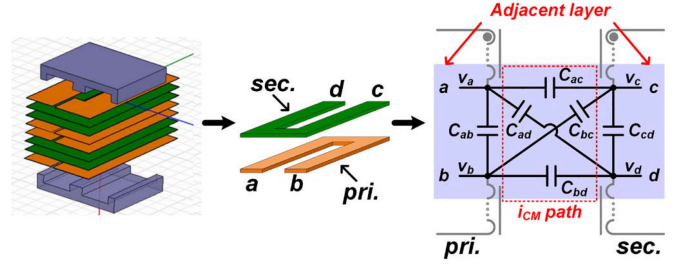


Fig. 14. Parasitic capacitor model of the planar transformer.

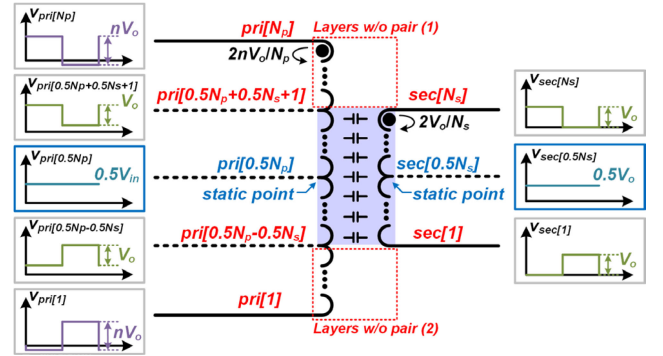


Fig. 15. Voltage waveforms at the primary and secondary layers of the transformer.

### III. LAYER ARRANGEMENT OF PT IN THE PROPOSED CONVERTER

The proposed converter has a smaller CM current flowing through the parasitic capacitors in the transformer, according to the analysis in Section II. However, the parasitic capacitor model of the transformer in Fig. 1 does not include the effect of parasitic capacitors between each winding. In the PT, each layer of the transformer contains the primary or secondary winding, and there are large parasitic capacitances between adjacent layers, as shown in Fig. 14. Thus, parasitic capacitors should be considered to analyze the CM current in the transformer. The CM current between adjacent layers  $i_{CM,L}$  is similar to (1). If the adjacent layers have the same number of turns and symmetric layout, parasitic capacitances can be assumed as the same value. Thus,  $i_{CM,L}$  can be calculated as follows:

$$i_{CM,L} = (C_{ac} + C_{ad}) \left( \frac{dv_a}{dt} + \frac{dv_b}{dt} - \frac{dv_c}{dt} - \frac{dv_d}{dt} \right) \quad (43)$$

where  $C_{ac}$  and  $C_{ad}$  are the parasitic capacitors between adjacent primary and secondary layers in the transformer, and  $v_a$ ,  $v_b$ ,  $v_c$ , and  $v_d$  are the voltage versus ground at the point  $a$ ,  $b$ ,  $c$ , and  $d$ , respectively.

According to (43), if the  $dv/dt$  characteristics of the voltage potential versus ground of adjacent primary and secondary layers are the same,  $i_{CM,L}$  is zero. Fig. 15 shows the voltage potential versus ground at the primary and secondary layers of the transformer. The voltages of the first layer and  $N_p$ th layer on the primary side change with the amplitude of  $nV_o$  based on  $0.5V_{in}$ , and the amplitude changes by  $2nV_o/N_p$  per turn. The voltage potential of the  $0.5N_p$ th layer on the primary side  $v_{pri[0.5Np]}$  becomes  $0.5V_{in}$ . Thus,  $dv/dt$  of  $v_{pri[0.5Np]}$  is

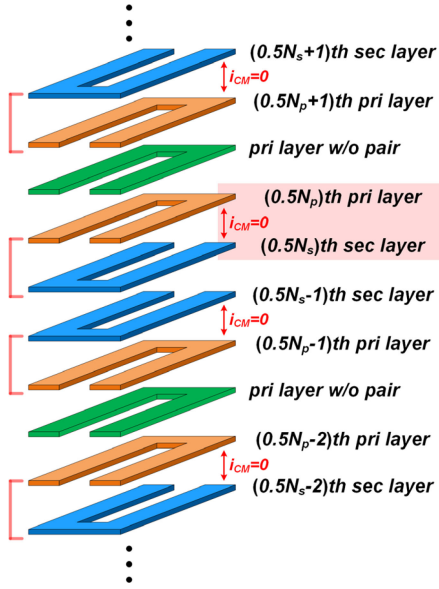


Fig. 16. Winding layout of the transformer in the proposed converter.

zero, which means the static point, as shown in Fig. 15. The voltages of the first layer and  $N_s$ th layer on the secondary side change with the amplitude of  $V_o$  on the basis of  $0.5V_o$ , and the amplitude changes by  $2V_o/N_s$  per turn. The voltage potential of the  $0.5N_s$ th layer on the secondary side  $v_{\text{sec}[0.5N_s]}$  becomes  $0.5V_o$ . Therefore, the  $dv/dt$  characteristic of  $v_{\text{sec}[0.5N_s]}$  is zero, which means the static point, as shown in Fig. 15. There is no difference of  $dv/dt$  between the  $0.5N_p$ th layer of the primary side and  $0.5N_s$ th layer of the secondary side. The voltage–amplitude–variation per turn of both sides is the same because  $n$  is  $N_p/N_s$ . Therefore, the primary and secondary layers can have the same  $dv/dt$  characteristic if primary and secondary layers are overlapped one by one based on the  $0.5N_p$ th layer for the primary side and  $0.5N_s$ th layer for the secondary side, as shown in Fig. 16.

If  $N_p$  is equal to  $N_s$ , every primary and secondary layer has its pair. However, the layers without pair should be considered because  $N_p$  and  $N_s$  are normally different. This section will explain the case when  $N_p$  is larger than  $N_s$ . The layers without pair are green layers in Fig. 16, which are located between the primary layers that have their pair. There is no CM current flowing through those layers because the CM current does not flow between the parasitic capacitors of the same side of the transformer.

The conventional and proposed converters have 20 layers in the PT, 12 primary layers, and 8 secondary layers. The whole layer arrangements of the PT in the conventional and proposed converters are given in Table III. The transformer of the conventional converter is composed of the interleaved winding structure and it results in a large CM current between primary and secondary layers. Although the transformer of the proposed converter also has an interleaved winding structure, there is no CM current between primary and secondary layers because the adjacent layers have the same  $dv/dt$  characteristic.

TABLE III  
WINDING LAYOUT OF TRANSFORMERS IN CONVENTIONAL AND PROPOSED CONVERTERS

Layers	Conv.	Prop.
20th	sec[1]	pri[1]
19th	pri[1]	pri[10]
18th	sec[2]	sec[8]
17th	pri[2]	sec[7]
16th	pri[3]	pri[9]
15th	sec[3]	pri[12]
14th	pri[4]	pri[8]
13th	pri[5]	sec[6]
12th	sec[4]	sec[5]
11th	pri[6]	pri[7]
10th	pri[7]	pri[1]
9th	sec[5]	pri[6]
8th	pri[8]	sec[4]
7th	pri[9]	sec[3]
6th	sec[6]	pri[5]
5th	pri[10]	pri[4]
4th	pri[11]	sec[2]
3rd	sec[7]	sec[1]
2nd	pri[12]	pri[3]
1st	sec[8]	pri[2]

pri[ $n$ ]: the  $n$ th primary winding of the transformer. sec[ $m$ ]: the  $m$ th secondary winding of the transformer.

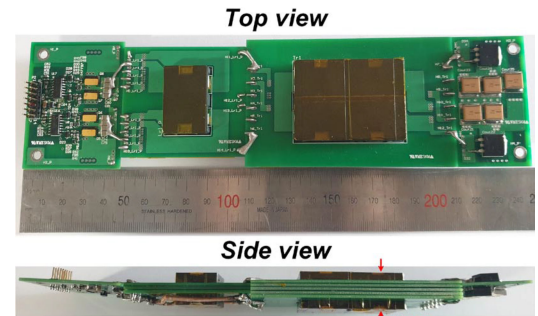


Fig. 17. Prototype of the proposed converter.

#### IV. EXPERIMENTAL RESULTS

Prototypes of both conventional and proposed converters are implemented with 1.5-kW FB *LLC* resonant converter, and the design specifications are as follows: input voltage is 400 V, output voltage is 270–420 V, and resonant frequency is 500 kHz. The prototype of the proposed converter is shown in Fig. 17 and the detailed component list of prototype converters is presented in Table IV. Each component is selected by considering the maximum voltage and current across components with a reasonable margin.

##### A. Voltage Waveforms of Prototype Converters

Fig. 18 shows the experimental waveforms of the conventional converter, and the voltage waveforms of the primary side  $v_{\text{pri,conv}}$ , secondary side  $v_{\text{sec,conv}}$ , and  $i_{Lr,c}$  are presented. Two voltage waveforms show the voltage potential of two adjacent

TABLE IV  
COMPONENT LIST OF CONVENTIONAL AND PROPOSED CONVERTERS

	Conventional converter	Proposed converter
Primary switches ( $Q_1, Q_2, Q_3,$ and $Q_4$ )	GS66508T ( $V_{ds,max} = 650$ V and $I_{DS,avg} = 30$ A)	
Transformers ( $L_{m,c}$ and $L_{m,p}$ )	ELP 38/8/25 * 2 (Material: N49. $L_{m,c}$ and $L_{m,p} = 40$ $\mu$ H and turns-ratio= 12:8)	
Resonant inductors ( $L_{r1}, L_{r1},$ and $L_{r2}$ )	ELP 32/6/20 (Material: N49. $L_r = 11.2$ $\mu$ H)	ELP 32/6/20 (Material: N49. $L_{r1}$ and $L_{r2} = 5.6$ $\mu$ H)
Resonant capacitors ( $C_r, C_{r1},$ and $C_{r2}$ )	GRM32D7U3A222JW31L ( $C_r = 8.8$ nF, Quantity: 4)	GRM32D7U3A222JW31L ( $C_{r1}$ and $C_{r2} = 17.6$ nF, Quantity: 8 and 8)
Rectifier diodes ( $D_1, D_2, D_3,$ and $D_4$ )	SCS210AJ ( $V_R = 650$ V and $I_F = 10$ A)	
CM choke ( $L_{CM,conv}$ and $L_{CM,prop}$ )	B64290L0082 (Material: N30, $L_{CM,conv} = 174$ mH, 140turns)	B64290L0618 (Material: N30, $L_{CM,prop} = 5$ mH, 34turns)
Y capacitor ( $C_Y$ )	B32529C8332J000 ( $C_Y = 3300$ pF)	

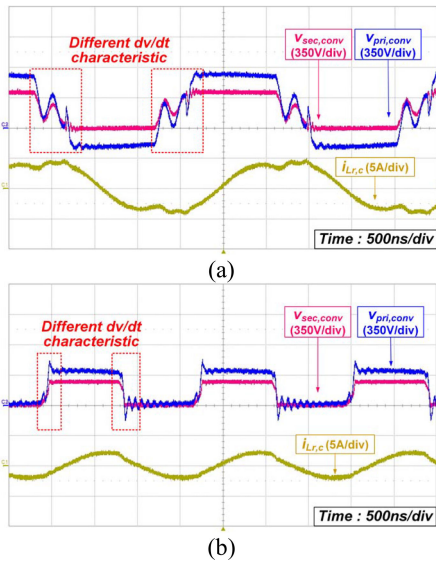


Fig. 18. Voltage waveforms of the conventional converter. (a) At  $V_o = 420$  V. (b) At  $V_o = 270$  V.

layers. Fig. 18(a) shows waveforms when  $V_o$  is 420 V and Fig. 18(b) presents the waveforms when  $V_o$  is 270 V. Both operations have the different  $dv/dt$  characteristic for the adjacent layers and it generates the large CM noise.

Fig. 19 presents the experimental waveforms of the proposed converter, and the voltage waveforms of the primary side  $v_{pri,prop}$ , secondary side  $v_{sec,prop}$ , and resonant inductor current  $i_{Lr,p}$  are presented. Two voltage waveforms show the voltage potential of two adjacent layers. Fig. 19(a) shows waveforms when  $V_o$  is 420 V and Fig. 19(b) shows waveforms when  $V_o$  is 270 V. Both operations when  $V_o$  is 420 and 270 V have the same  $dv/dt$  characteristic for the adjacent layers, and it results in low CM noise.

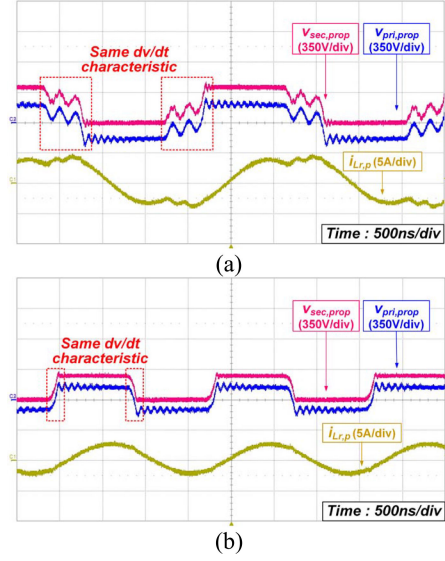


Fig. 19. Voltage waveforms of the proposed converter. (a) At  $V_o = 420$  V. (b) At  $V_o = 270$  V.

### B. CM Noise of Conventional and Proposed Converter

CM noises are not only generated from parasitic capacitors of the transformer but also can be generated from parasitic capacitors between two phase-leg midpoints and protective earth  $C_{mid}$ . However, it is assumed that the CM noise generated from  $C_{mid}$  is very small because  $C_{mid}$  is generated between the heat sink and earth ground, and there is no heat sink in the prototype converter. Therefore, most of the CM noise differences between the conventional and proposed converter come from the variation of the circuit and layer arrangement of the PT.

Fig. 20 shows the measured CM noise of the conventional and proposed converter without the EMI filter. The CM noise is measured with the line impedance stabilization network named NNHV 8123 and spectrum analyzer named EA-300. In Fig. 20(a) and (c), the first peak locates around 500 kHz, which is the operating switching frequency when  $V_o$  is 270 V. In Fig. 20(b) and (d), the first peak locates around 340 kHz, which is the operating switching frequency when  $V_o = 420$  V. Most of the peak values occurs at the multiples of each switching frequency. The CM noise peak of the proposed converter has a smaller value under almost every frequency range due to the balanced resonant tank and proposed winding layout. The CM noise at the fundamental frequency is increased according to the rise of  $V_o$  in the conventional converter. However, it is almost the same regardless of the  $V_o$  condition in the proposed converter because the  $dv/dt$  characteristic of adjacent layers in the transformer is almost the same under every occasion.

### C. Design of the Resonant Tank

In the proposed converter, the design process of the resonant tank is the same as the conventional converter. The resonant tank is designed to have the same resonant frequency and voltage gain, and the resonant inductor and capacitor are divided into two equal components, respectively.  $L_{r1} = L_{r2}$  and  $C_{r1} = C_{r2}$  due to

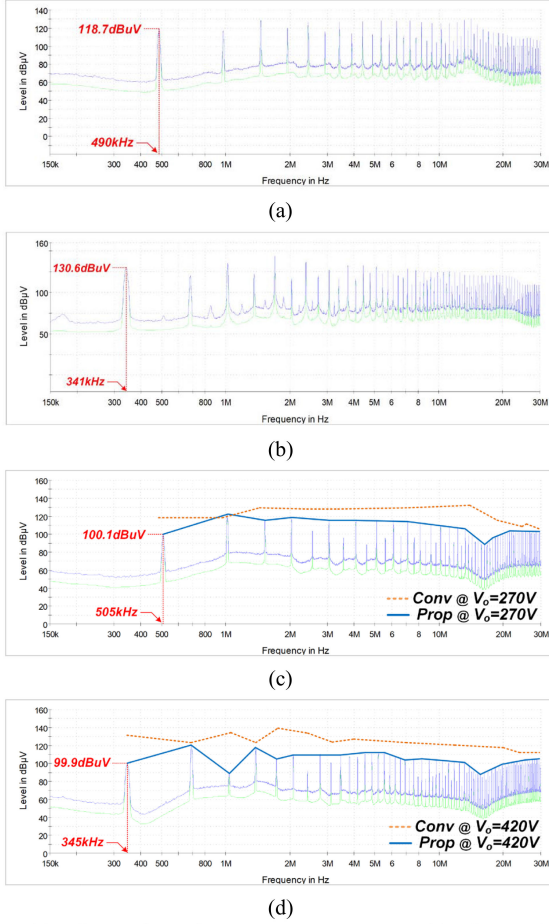


Fig. 20. CM noise of prototype converters. (a) Conventional converter at  $V_o = 270$  V. (b) Conventional converter at  $V_o = 420$  V. (c) Proposed converter at  $V_o = 270$  V. (d) Proposed converter at  $V_o = 420$  V.

the balanced resonant tank structure, and the total inductance of series-connected  $L_{r1}$  and  $L_{r2}$  is  $2L_{r1}$ , and the total capacitance of series-connected  $C_{r1}$  and  $C_{r2}$  is  $0.5C_{r1}$ . Thus,  $L_{r1} = L_{r2} = 0.5L_r$  and  $C_{r1} = C_{r2} = 2C_r$  for the same resonant frequency.

The voltage gain of the LLC resonant converter is obtained by using the fundamental harmonic approximation (FHA) [29]. Utilizing the FHA method, the voltage gain of the conventional converter  $M_c$  and that of the proposed converter  $M_p$  can be calculated as follows:

$$M_c = \frac{V_{o,c}^F}{V_{in,c}^F} = \frac{1}{1 + \frac{1}{k_c} \left(1 - \frac{1}{F_c^2}\right)^2 + \left\{ \left(F_c - \frac{1}{F_c}\right) Q_c \right\}} \quad (44)$$

$$M_p = \frac{V_{o,p}^F}{V_{in,p}^F} = \frac{1}{1 + \frac{1}{k_p} \left(1 - \frac{1}{F_p^2}\right)^2 + \left\{ \left(F_p - \frac{1}{F_p}\right) Q_p \right\}} \quad (45)$$

where  $V_{o,c}^F$  and  $V_{in,c}^F$  are the fundamental components of the  $V_o$  and  $V_{in}$  for the conventional converter,  $k_c$  is  $L_{m,c}/L_r$ ,  $F_c$  is  $f_s/f_{r,c}$ ,  $f_s$  is the switching frequency,  $f_{r,c}$  is the resonant frequency of the conventional converter,  $Q_c = (L_r/C_r)^{0.5}/R_{ac}$ ,  $R_{ac}$  is  $8R_o n^2/\pi^2$ ,  $R_o$  is the output resistance,  $V_{o,p}^F$  and  $V_{in,p}^F$  are the fundamental components of  $V_o$  and  $V_{in}$  for the proposed converter,  $k_p$  is  $L_{m,p}/(2L_{r1})$ ,  $F_p$  is  $f_s/f_{r,p}$ ,  $f_{r,p}$  is the resonant frequency of the proposed converter, and  $Q_p = (2L_{r1}/(0.5C_{r1}))^{0.5}/R_{ac}$ .

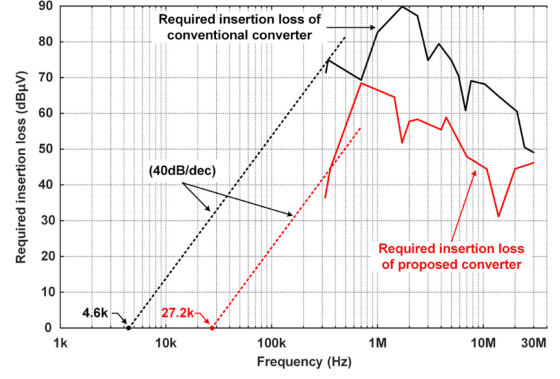


Fig. 21. Required insertion loss for the conventional and proposed converter.

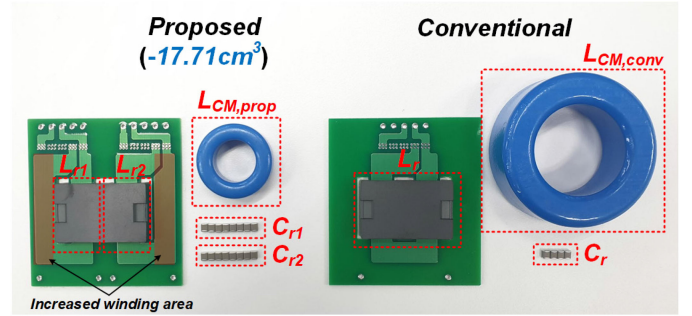


Fig. 22. Volume comparison of the resonant tank and CM inductor.

As aforementioned earlier,  $L_{r1} = L_{r2} = 0.5L_r$  and  $C_{r1} = C_{r2} = 2C_r$  for the same resonant tank, and it results in same  $M_c$  and  $M_p$  according to (44) and (45). The voltage across the resonant inductor in the proposed converter is half of that in the conventional converter. The effective cross-sectional area for the resonant inductor of the conventional converter  $A_{e,c}$  and that of the proposed converter  $A_{e,p}$  can be calculated as follows:

$$A_{e,p} = 0.5 A_{e,c} = \frac{V_{Lr,p-peak}}{4N_{Lr} B_{max} f_{s,min}} \quad (46)$$

where  $V_{Lr,p-peak}$  is the peak voltage across the resonant inductor in the proposed converter,  $B_{max}$  is the maximum flux density, and  $f_{s,min}$  is the minimum operating frequency.

The size of the resonant inductor of the proposed converter is half of that of the conventional converter. The total inductor size of the conventional and proposed converter is the same. As aforementioned,  $C_{r1} = C_{r2} = 2C_r$  for the same voltage gain of the conventional and proposed converter. Each number of capacitors for  $C_{r1}$  and  $C_{r2}$  is doubled compared with that of  $C_r$ . Therefore, the total number of resonant capacitors becomes quadrupled in the proposed converter. Although the number of resonant capacitors becomes quadrupled in the proposed converter, they do not occupy a large area, as shown in Fig. 22.

#### D. Design of Expected EMI Filter

The EMI filter should be utilized to meet the EMI standard and the EMI filter is designed based on the EN55022B standard in this article. In [30], the required CM noise attenuation (required insertion loss)  $V_{req,CM}$  is calculated as follows:

$$(V_{req,CM})_{dB} = (V_{meas,CM})_{dB} - (V_{Limit})_{dB} + 3dB \quad (47)$$

where  $V_{\text{meas,CM}}$  is the measured CM noise amplitude,  $V_{\text{Limit}}$  is the quasi-peak CM noise limit, and 3 dB is for a safety margin.

From (47),  $V_{\text{req,CM}}$  of the conventional and proposed converter when  $V_o$  is 420 V is presented in Fig. 21. From the EMI standard, the required CM noise limit is different according to the switching frequency and  $V_{\text{req,CM}}$  represents the required amount of the CM noise to be reduced to satisfy the EMI standard for each switching frequency. The case when  $V_o$  is 420 V is the worst occasion in terms of the CM noise because  $dv/dt$  of the voltage potential at each layer in the transformer becomes the largest. The corner frequencies of the conventional converter  $f_{R,\text{conv}}$  and the proposed converter  $f_{R,\text{prop}}$  can be obtained as follows:

$$V_{\text{req,CM,conv}} = 40 \log \left( \frac{f_{\text{meas}}}{f_{R,\text{conv}}} \right) \quad (48)$$

$$V_{\text{req,CM,prop}} = 40 \log \left( \frac{f_{\text{meas}}}{f_{R,\text{prop}}} \right) \quad (49)$$

where  $f_{\text{meas}}$  is the frequency at  $V_{\text{meas,CM}}$ ,  $V_{\text{req,CM,conv}}$  is the required CM noise attenuation of the conventional converter, and  $V_{\text{req,CM,prop}}$  is the required CM noise attenuation of the proposed converter.

From (48) and (49),  $f_{R,\text{conv}}$  and  $f_{R,\text{prop}}$  can be calculated as 4.6 and 27.2 kHz, as shown in Fig. 21, respectively.  $LC$  CM filter is composed of the CM choke and  $Y$  capacitor  $C_Y$ .  $C_Y$  is limited by the leakage current limits for safety requirements [21] and  $C_Y$  is designed with 3300 pF in this case. The CM choke of the conventional converter  $L_{\text{CM,conv}}$  and the proposed converter  $L_{\text{CM,prop}}$  can be calculated as follows:

$$L_{\text{CM,conv}} = \frac{1}{2C_Y(2\pi f_{R,\text{conv}})^2} \quad (50)$$

$$L_{\text{CM,prop}} = \frac{1}{2C_Y(2\pi f_{R,\text{prop}})^2} \quad (51)$$

Using (50) and (51),  $L_{\text{CM,conv}}$  is 174 mH and  $L_{\text{CM,prop}}$  is 5 mH. Based on the N30 material, the CM choke of the conventional converter can be designed with B64290L0082, whose volume is 23.56 cm<sup>3</sup>, and that of the proposed converter can be applied as B64290L0618, whose volume is 3.08 cm<sup>3</sup>. Therefore, the decreased volume is 20.48 cm<sup>3</sup>, which means that the CM filter size of the proposed converter is reduced as 86.9% compared with that of the conventional converter. A comparison of the actual size of the resonant tank and CM choke in the conventional and proposed converter is shown in Fig. 23. Although the volume by the resonant capacitor and winding area of the resonant inductor is increased as 2.77 cm<sup>3</sup>, the proposed converter can reduce the volume as much as 17.71 cm<sup>3</sup>.

### E. Measured Efficiency

The efficiency of the prototype converter is measured according to the variation of  $V_o$ , as shown in Fig. 23. The efficiency of the conventional converter without the CM filter is almost the same as that of the proposed converter because it uses almost the same components and switching frequency. The conventional converter uses a large CM choke with a large number of turns. As

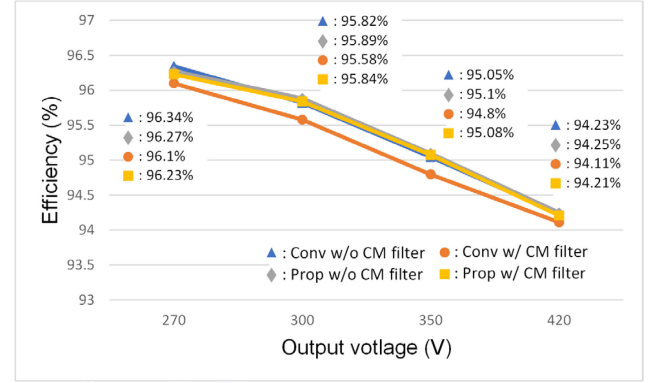


Fig. 23. Measured efficiency of the conventional and proposed converter.

a result, the conventional converter with the CM filter decreases efficiency due to the large conduction loss of the CM choke. On the other hand, the proposed converter uses a small CM choke with a small number of turns. Thus, the measured efficiency of the proposed converter with the CM filter is almost the same as that of the proposed converter without the CM filter.

## V. CONCLUSION

In this article, a low CM noise FB  $LLC$  resonant converter having a balanced resonant tank is proposed. In the proposed converter, resonant inductances and capacitances in the balanced resonant tank are the same, i.e.,  $L_{r1} = L_{r2}$  and  $C_{r1} = C_{r2}$ , and the CM current flowing through the parasitic capacitors of the transformer becomes zero. Moreover, the CM noise generated from parasitic capacitors between the primary and secondary layers is decreased by locating primary and secondary layers adjacently with the same  $dv/dt$  characteristics. A 1.5-kW prototype of the FB  $LLC$  resonant converter is fabricated to verify the performance of the proposed converter. The CM noise of the proposed converter at the fundamental frequency is 30.7 dB $\mu$ V smaller than that of the conventional converter when  $V_o$  is 420 V. Thus, the size of the EMI filter can be reduced by 83% for a single-stage  $LC$  CM filter and 59% for a multistage  $LCLC$  CM filter. As a result, the proposed converter can increase the power density for the FB  $LLC$  resonant converter by reducing the size of the EMI filter.

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## REFERENCES

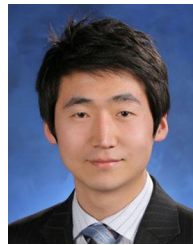
- [1] D. Cochrane, D. Y. Chen, and D. Boroyevic, "Passive cancellation of common-mode noise in power electronic circuits," *IEEE Trans. Power Electron.*, vol. 18, no. 3, pp. 756–763, May 2003.
- [2] Y. Chu, S. Wang, and Q. Wang, "Modeling and stability analysis of active/hybrid common-mode EMI filters for DC/DC power converters," *IEEE Trans. Power Electron.*, vol. 31, no. 9, pp. 6254–6263, Sep. 2016.
- [3] M. Shoyama, G. Li, and T. Ninomiya, "Balanced switching converter to reduce common-mode conducted noise," *IEEE Trans. Ind. Electron.*, vol. 50, no. 6, pp. 1095–1099, Dec. 2003.

- [4] S. Wang, P. Kong, and F. C. Lee, "Common mode noise reduction for boost converters using general balance technique," *IEEE Trans. Power Electron.*, vol. 22, no. 4, pp. 1410–1416, Jul. 2007.
- [5] L. Xie, X. Ruan, and Z. Ye, "Equivalent noise source: An effective method for analyzing common-mode noise in isolated power converters," *IEEE Trans. Ind. Electron.*, vol. 63, no. 5, pp. 2913–2924, May 2016.
- [6] H. Zhang, S. Wang, Y. Li, Q. Wang, and D. Fu, "Two-capacitor transformer winding capacitance models for common-mode EMI noise analysis in isolated DC–DC converters," *IEEE Trans. Power Electron.*, vol. 32, no. 11, pp. 8458–8469, Nov. 2017.
- [7] Y. P. Chan, B. M. H. Pong, N. K. Poon, and J. C. P. Liu, "Common-mode noise cancellation by an antiphase winding in multilayer isolated planar transformer," *IEEE Trans. Electromagn. Compat.*, vol. 56, no. 1, pp. 67–73, Feb. 2014.
- [8] K. Fu and W. Chen, "Evaluation method of Flyback converter behaviors on common-mode noise," *IEEE Access*, vol. 7, pp. 28019–28030, 2019.
- [9] Y. Chu and S. Wang, "A generalized common-mode current cancellation approach for power converters," *IEEE Trans. Ind. Electron.*, vol. 62, no. 7, pp. 4130–4140, Jul. 2015.
- [10] H.-I. Hsieh, L. Huwang, T.-C. Lin, and D. Chen, "Use of a  $C_z$  common-mode capacitor in two-wire and three-wire offline power supplies," *IEEE Trans. Ind. Electron.*, vol. 55, no. 3, pp. 1435–1443, Mar. 2008.
- [11] D. Fu, S. Wang, P. Kong, F. C. Lee, and D. Huang, "Novel techniques to suppress the common-mode EMI noise caused by transformer parasitic capacitances in DC–DC converters," *IEEE Trans. Ind. Electron.*, vol. 60, no. 11, pp. 4968–4977, Nov. 2013.
- [12] L. Xie, X. Ruan, and Z. Ye, "Reducing common mode noise in phase-shifted full-bridge converter," *IEEE Trans. Ind. Electron.*, vol. 65, no. 10, pp. 7866–7877, Oct. 2018.
- [13] Y. Li, H. Zhang, S. Wang, H. Sheng, C. P. Chng, and S. Lakshminathan, "Investigating switching transformers for common mode EMI reduction to remove common mode EMI filters and Y-capacitors in flyback converters," *IEEE J. Emerg. Sel. Topics Power Electron.*, vol. 6, no. 4, pp. 2287–2301, Dec. 2018.
- [14] S. Zhang and X. Wu, "Low common mode noise half-bridge LLC DC–DC converter with an asymmetric center tapped rectifier," *IEEE Trans. Power Electron.*, vol. 34, no. 2, pp. 1032–1037, Feb. 2019.
- [15] L. Pentti and O. Hyvonen, "Electrically decoupled integrated transformer having at least one grounded electric shield," U.S. Patent 7 733 205 B2, Jun. 8, 2010.
- [16] J. Lu and F. Dawson, "Characterizations of high frequency planar transformer with a novel comb-shaped shield," *IEEE Trans. Magn.*, vol. 47, no. 10, pp. 4493–4496, Oct. 2011.
- [17] H. Chen and J. Xiao, "Determination of transformer shielding foil structure for suppressing common-mode noise in flyback converters," *IEEE Trans. Magn.*, vol. 52, no. 12, Dec. 2016, Art. no. 8401809.
- [18] L. Xie, X. Ruan, Q. Ji, and Z. Ye, "Shielding-cancellation technique for suppressing common-mode EMI in isolated power converters," *IEEE Trans. Ind. Electron.*, vol. 62, no. 5, pp. 2814–2822, May 2015.
- [19] Y. Yang, D. Huang, F. C. Lee, and Q. Li, "Transformer shielding technique for common mode noise reduction in isolated converters," in *Proc. IEEE Energy Convers. Congr. Expo.*, Sep. 2017, pp. 4149–4153.
- [20] C. Fei, Y. Yang, Q. Li, and F. C. Lee, "Shielding technique for planar matrix transformers to suppress common-mode EMI noise and improve efficiency," *IEEE Trans. Ind. Electron.*, vol. 65, no. 2, pp. 1263–1272, Feb. 2018.
- [21] Y. Bai, X. Yang, X. Li, D. Zhang, W. Hu, and W. Chen, "Conducted EMI mitigation schemes in isolated switching-mode power supply without the need of a Y-capacitor," *IEEE Trans. Power Electron.*, vol. 32, no. 4, pp. 2687–2703, Apr. 2017.
- [22] Z. Zhang, B. He, D.-D. Hu, X. Ren, and Q. Chen, "Common-mode noise modeling and reduction for 1-MHz eGaN multioutput dc–dc converters," *IEEE Trans. Power Electron.*, vol. 34, no. 4, pp. 3239–3254, Apr. 2019.
- [23] M. A. Saket, N. Shafiei, and M. Ordonez, "Planar transformers with near-zero common-mode noise for flyback and converters," *IEEE Trans. Power Electron.*, vol. 33, no. 2, pp. 1554–1571, Feb. 2018.
- [24] M. A. Saket, M. Ordonez, M. Craciun, and C. Botting, "Improving planar transformers for LLC resonant converters: Paired layers interleaving," *IEEE Trans. Power Electron.*, vol. 34, no. 12, pp. 11813–11832, Dec. 2019.
- [25] H.-N. Vu and W. Choi, "A novel dual full-bridge LLC resonant converter for CC and CV charges of batteries for electric vehicles," *IEEE Trans. Ind. Electron.*, vol. 65, no. 3, pp. 2212–2225, Mar. 2018.
- [26] H. Wang and Z. Li, "A PWM LLC type resonant converter adapted to wide output range in PEV charging applications," *IEEE Trans. Power Electron.*, vol. 33, no. 5, pp. 3791–3801, May 2018.
- [27] B. Yang, F. C. Lee, A. J. Zhang, and G. Huang, "LLC resonant converter for front end DC/DC conversion," in *Proc. 17th Annu. IEEE Appl. Power Electron. Conf. Expo.*, Mar. Mar, pp. 1108–1112.
- [28] B.-C. Kim, K.-B. Park, C.-E. Kim, B.-H. Lee, and G.-W. Moon, "LLC resonant converter with adaptive link-voltage variation for a high-power-density adapter," *IEEE Trans. Power Electron.*, vol. 25, no. 9, pp. 2248–2252, Sep. 2010.
- [29] R. L. Steigerwald, "A comparison of half-bridge resonant converter topologies," *IEEE Trans. Power Electron.*, vol. 3, no. 2, pp. 174–182, Apr. 1988.
- [30] F.-Y. Shih, D.-Y. Chen, Y.-P. Wu, and Y.-T. Chen, "A procedure for designing EMI filters for AC line applications," *IEEE Trans. Power Electron.*, vol. 11, no. 1, pp. 170–181, Jan. 1996.



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